

HVL396C Variable Capacitance Diode for VCO

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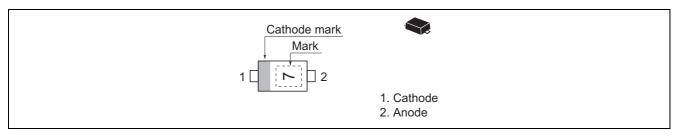
Features

- High capacitance ratio. (n = 2.62 min)
- Low series resistance. (rs = $0.40 \Omega \text{ max}$)
- Extremely small Flat Package (EFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HVL396C	7	EFP

Pin Arrangement





HVL396C

Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Reverse voltage	V _R	10	V
Junction temperature	Tj	125	°C
Storage temperature	Tstg	–55 to +125	۵°

Electrical Characteristics

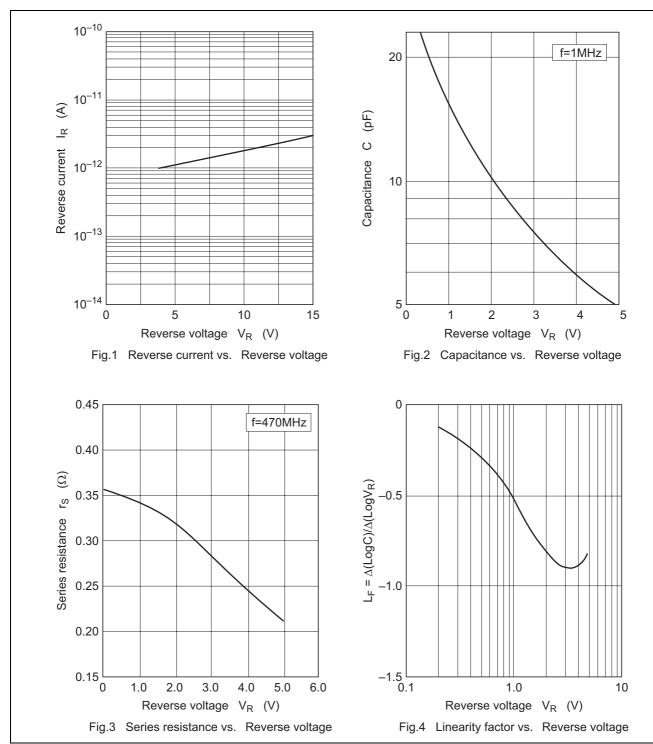
						$(Ta = 25^{\circ}C)$
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I _{R1}	—	—	10	nA	V _R = 10 V
	I _{R2}	_	—	50		V _R = 10 V, Ta = 60°C
Capacitance	C ₁	14.6	—	15.8	pF	$V_R = 1 V, f = 1 MHz$
	C ₄	5.20	—	5.80		$V_R = 4 V, f = 1 MHz$
Capacitance ratio	n	2.62	—	—	—	C ₁ / C ₄
Series resistance	r _s	_	_	0.40	Ω	V _R = 1 V, f = 470 MHz

Notes: 1. Please do not use the soldering iron due to avoid high stress to the EFP package.

2. The material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.



HVL396C

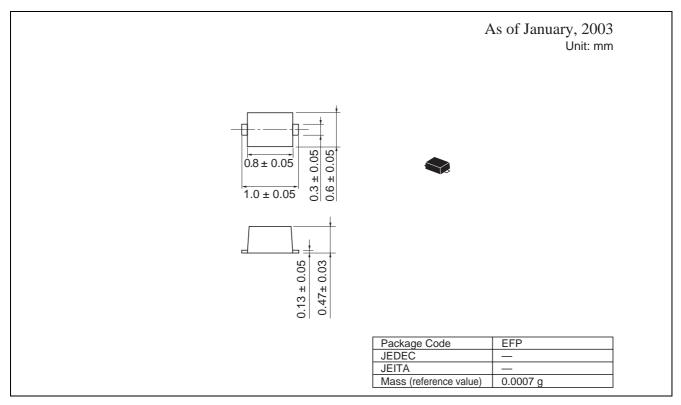


Main Characteristic



HVL396C

Package Dimensions





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